Title (en)

OVEN FOR COOKING FOOD PRODUCTS AND METHOD FOR COOKING FOOD PRODUCTS WITH SAID OVEN

Title (de)

OFEN ZUM KOCHEN VON LEBENSMITTELPRODUKTEN UND VERFAHREN ZUM KOCHEN VON LEBENSMITTELPRODUKTEN MIT DIESEM OFEN

Title (fr)

FOUR POUR LA CUISSON DE PRODUITS ALIMENTAIRES ET PROCÉDÉ DE CUISSON DE PRODUITS ALIMENTAIRES AVEC LEDIT FOUR

Publication

EP 4253844 A1 20231004 (EN)

Application

EP 23165684 A 20230330

Priority

IT 202200006305 A 20220330

Abstract (en)

Oven for cooking food products, which comprises a support structure (2) internally delimiting a cooking chamber (3), a cooking surface (4) placed within the cooking chamber (3) and heating means (5), mechanically connected to the support structure (2) and placed to heat at least the cooking surface (4).The oven comprises, moreover, a fixed first temperature sensor (6), mounted on the support structure (2), pointed towards the cooking surface (4) and configured for detecting at least one surface temperature value (Ts) of a first measurement area (A1) on the cooking surface (4).In addition the oven is provided with a logic control unit (7), mechanically connected to the support structure (2) and comprising a first comparison module (C1) configured for comparing at least the surface temperature value (Ts) with a threshold surface temperature value (Tss1), and at least one user interface (8), configured for receiving a comparison signal from the first comparison module (C1) and emitting a warning signal based on the comparison signal.

IPC 8 full level

F24C 7/08 (2006.01)

CPC (source: EP)

F24C 7/085 (2013.01); **F24C 7/087** (2013.01)

Citation (applicant)

- US 2021404745 A1 20211230 - JOHNSON ERIC SCOTT [US], et al
- US 2017332841 A1 20171123 - REISCHMANN MICHAEL [US]

Citation (search report)

- [Y] US 2021404745 A1 20211230 - JOHNSON ERIC SCOTT [US], et al
- [A] US 2017332841 A1 20171123 - REISCHMANN MICHAEL [US]
- [Y] US 2016283822 A1 20160929 - IMAI HIROHISA [JP], et al
- [A] WO 2012105233 A1 20120809 - MITSUBISHI ELECTRIC CORP [JP], et al
- [A] US 2017017248 A1 20170119 - ARMSTRONG JAMES LEE [US], et al
- [Y] EP 2333420 A1 20110615 - INDESIT CO SPA [IT]
- [A] KR 20060032472 A 20060417 - LG ELECTRONICS INC [KR]
- [XY] EP 1076475 B1 20050727 - TOSHIBA KK [JP]

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC ME MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA

Designated validation state (EPC)

KH MA MD TN

DOCDB simple family (publication)

EP 4253844 A1 20231004; IT 202200006305 A1 20230930

DOCDB simple family (application)

EP 23165684 A 20230330; IT 202200006305 A 20220330